

Octal 3-STATE Transceiver

MM74HC245A

General Description

The MM74HC245A 3-STATE bidirectional buffer utilizes advanced silicon-gate CMOS technology, and is intended for two-way asynchronous communication between data buses. It has high drive current outputs which enable high speed operation even when driving large bus capacitances. This circuit possesses the low power consumption and high noise immunity usually associated with CMOS circuitry, yet has speeds comparable to low power Schottky TTL circuits.

This device has an active LOW enable input G and a direction control input, DIR. When DIR is HIGH, data flows from the A inputs to the B outputs. When DIR is LOW, data flows from the B inputs to the A outputs. The MM74HC245A transfers true data from one bus to the other.

This device can drive up to 15 LS-TTL Loads, and does not have Schmitt trigger inputs. All inputs are protected from damage due to static discharge by diodes to VCC and ground.

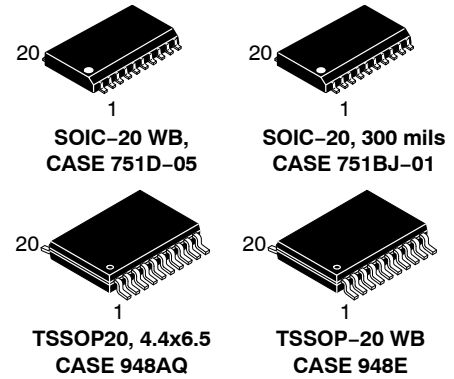
Features

- Typical Propagation Delay: 13 ns
- Wide Power Supply Range: 2 V to 6 V
- Low Quiescent Current: 160 μ A Maximum (74HC)
- 3-STATE Outputs for Connection to Bus Oriented Systems
- High Output Current: 6 mA (Minimum)
- Same as the 645
- These are Pb-Free Devices

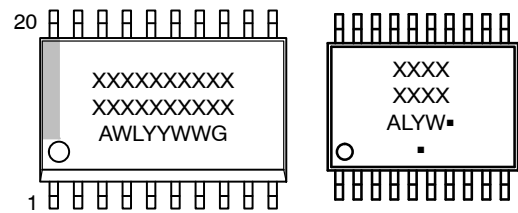
TRUTH TABLE

Control Inputs		Operation
\bar{G}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

NOTE: H = HIGH Level
L = LOW Level
X = Irrelevant



MARKING DIAGRAM

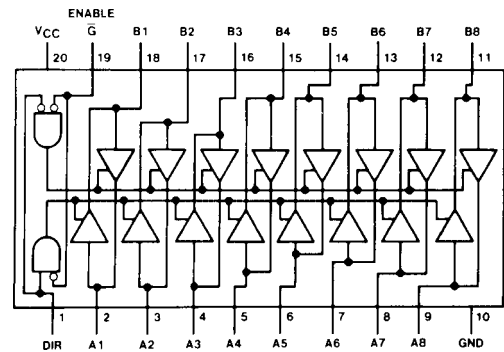


XXXXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G, \blacksquare = Pb-Free Package

(Note: Microdot may be in either location)

CONNECTION DIAGRAM

Pin Assignment for SOIC and TSSOP



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

MM74HC245A

Logic Diagram

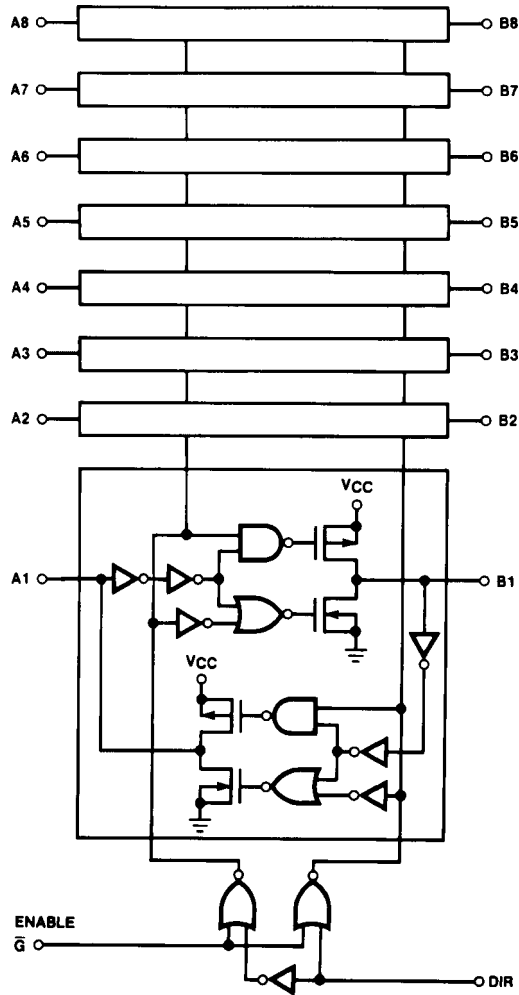


Figure 1. Logic Diagram

ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Rating	Unit
V_{CC}	Supply Voltage	-0.5 to +7.0	V
V_{IN}	DC Input Voltage DIR and \bar{G} pins	-0.5 to $V_{CC} + 0.5$	V
V_{IN}, V_{OUT}	DC Input/Output Voltage	-0.5 to $V_{CC} + 0.5$	V
I_{CD}	Clamp Diode Current	± 20	mA
I_{OUT}	DC Output Current, per pin	± 35	mA
I_{CC}	DC V_{CC} or GND Current, per pin	± 70	mA
T_{STG}	Storage Temperature Range	-65 to +150	$^{\circ}C$
P_D	Power Dissipation (Note 2)	600	mW
	S.O. Package only	500	
T_L	Lead Temperature (Soldering 10 seconds)	260	$^{\circ}C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.

2. Power dissipation temperature derating – plastic “N” package: -12 mW/ $^{\circ}C$ from 65 $^{\circ}C$ to 85 $^{\circ}C$.

MM74HC245A

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Supply Voltage	2	6	V	
V_{IN}, V_{OUT}	DC Input or Output Voltage	0	V_{CC}	V	
T_A	Operating Temperature Range	-55	+125	°C	
t_r, t_f	Input Rise/Fall Times	$V_{CC} = 2.0\text{ V}$	-	1000	ns
		$V_{CC} = 4.5\text{ V}$	-	500	
		$V_{CC} = 6.0\text{ V}$	-	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (Note 3)

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$		$T_A = -40^\circ\text{C}$	$T_A = -55^\circ\text{C}$	Unit
				Typ.	Guaranteed Limits			
V_{IH}	Minimum HIGH Level Input Voltage		2.0	-	1.50	1.50	1.50	V
			4.5	-	3.15	3.15	3.15	
			6.0	-	4.20	4.20	4.20	
V_{IL}	Maximum LOW Level Input Voltage		2.0	-	0.50	0.50	0.50	V
			4.5	-	1.35	1.35	1.35	
			6.0	-	1.80	1.80	1.80	
V_{OH}	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $ I_{OUT} \leq 20\ \mu\text{A}$	2.0	2.0	1.9	1.9	1.9	V
			4.5	4.5	4.4	4.4	4.4	
			6.0	6.0	5.9	5.9	5.9	
		4.5	4.20	3.98	3.84	3.70		
				6.0	5.70	5.48	5.34	
V_{OL}	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} , $ I_{OUT} \leq 20\ \mu\text{A}$	2.0	0	0.1	0.1	0.1	V
			4.5	0	0.1	0.1	0.1	
			6.0	0	0.1	0.1	0.1	
		4.5	0.20	0.26	0.33	0.40		
				6.0	0.20	0.26	0.33	
I_{IN}	Input Leakage Current (G and DIR)	$V_{IN} = V_{CC}$ or GND	6.0	-	± 0.1	± 1.0	± 1.0	μA
I_{OZ}	Maximum 3-STATE Output Leakage Current	$V_{OUT} = V_{CC}$ or GND Enable $\bar{G} = V_{IH}$	6.0	-	± 0.5	± 5.0	± 10	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0\ \mu\text{A}$	6.0	-	8.0	80	160	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. For a power supply of $5\text{ V} \pm 10\%$ the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5\text{ V}$ and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

MM74HC245A

AC ELECTRICAL CHARACTERISTICS

($V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $t_r = t_f = 6\text{ ns}$)

Symbol	Parameter	Conditions	Typ.	Guaranteed Limit	Unit
t_{PHL} , t_{PLH}	Maximum Propagation Delay	$C_L = 45\text{ pF}$	12	17	ns
t_{PZL} , t_{PZH}	Maximum Output Enable Time	$R_L = 1\text{ k}\Omega$, $C_L = 45\text{ pF}$	24	35	ns
t_{PLZ} , t_{PHZ}	Maximum Output Disable Time	$R_L = 1\text{ k}\Omega$, $C_L = 5\text{ pF}$	18	25	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

($V_{CC} = 2.0\text{ V to }6.0\text{ V}$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$, unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$		$T_A = -40^\circ\text{C}$ to 85°C	$T_A = -55^\circ\text{C}$ to 125°C	Unit
				Typ.	Guaranteed Limits			
t_{PHL} , t_{PLH}	Maximum Propagation Delay	$C_L = 50\text{ pF}$ $C_L = 150\text{ pF}$	2.0	31	90	113	135	ns
				41	96	116	128	
			4.5	13	18	23	27	
t_{PZH} , t_{PZL}	Maximum Output Enable Time	$R_L = 1\text{ k}\Omega$ $C_L = 50\text{ pF}$ $C_L = 150\text{ pF}$	2.0	71	190	240	285	ns
				81	240	300	360	
			4.5	26	38	48	57	
t_{PHZ} , t_{PLZ}	Maximum Output Disable Time	$R_L = 1\text{ k}\Omega$ $C_L = 50\text{ pF}$	2.0	39	135	169	203	ns
				4.5	20	27	34	
			6.0	18	23	29	34	
t_{TLH} , t_{THL}	Output Rise and Fall Time	$C_L = 50\text{ pF}$	2.0	20	60	75	90	ns
				4.5	6	12	15	
			6.0	5	10	13	15	
C_{PD}	Power Dissipation Capacitance (Note 4)	$\bar{G} = V_{IL}$ $\bar{G} = V_{IH}$		50 5	-	-	-	pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF
$C_{IN/OUT}$	Maximum Input/Output Capacitance, A or B			15	20	20	20	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

MM74HC245A

ORDERING INFORMATION

Device	Package	Shipping [†]
MM74HC245AWM	SOIC-20 WB (Pb-Free)	38 Units / Tube
MM74HC245AWMX	SOIC-20 (Pb-Free)	1000 / Tape & Reel
MM74HC245AMTC	TSSOP-20 WB (Pb-Free)	75 Units / Tube
MM74HC245AMTCX	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MECHANICAL CASE OUTLINE

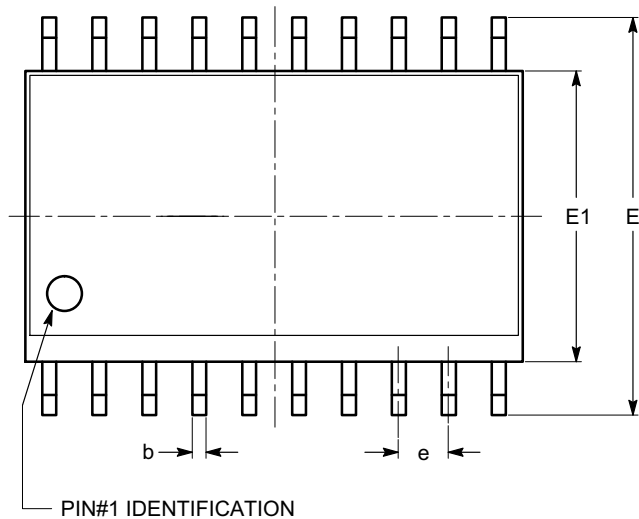
PACKAGE DIMENSIONS

ON Semiconductor®



SOIC-20, 300 mils
CASE 751BJ-01
ISSUE O

DATE 19 DEC 2008



TOP VIEW

SYMBOL	MIN	NOM	MAX
A	2.36	2.49	2.64
A1	0.10		0.30
A2	2.05		2.55
b	0.31	0.41	0.51
c	0.20	0.27	0.33
D	12.60	12.80	13.00
E	10.01	10.30	10.64
E1	7.40	7.50	7.60
e	1.27 BSC		
h	0.25		0.75
L	0.40	0.81	1.27
θ	0°		8°
$\theta 1$	5°		15°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-013.

DOCUMENT NUMBER:	98AON34287E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-20, 300 MILS	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015

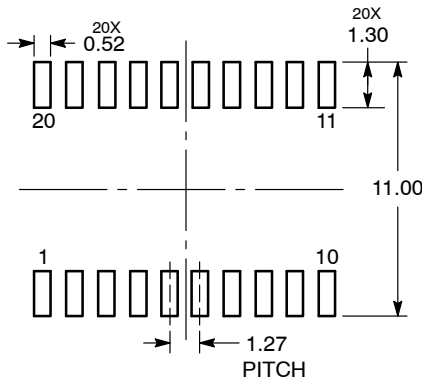


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

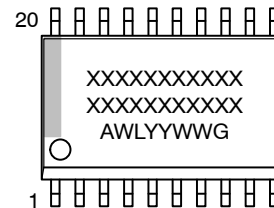
RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98ASB42343B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-20 WB	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-20 WB
CASE 948E
ISSUE D

DATE 17 FEB 2016

SCALE 2:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

DOCUMENT NUMBER:	98ASH70169A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP-20 WB	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE

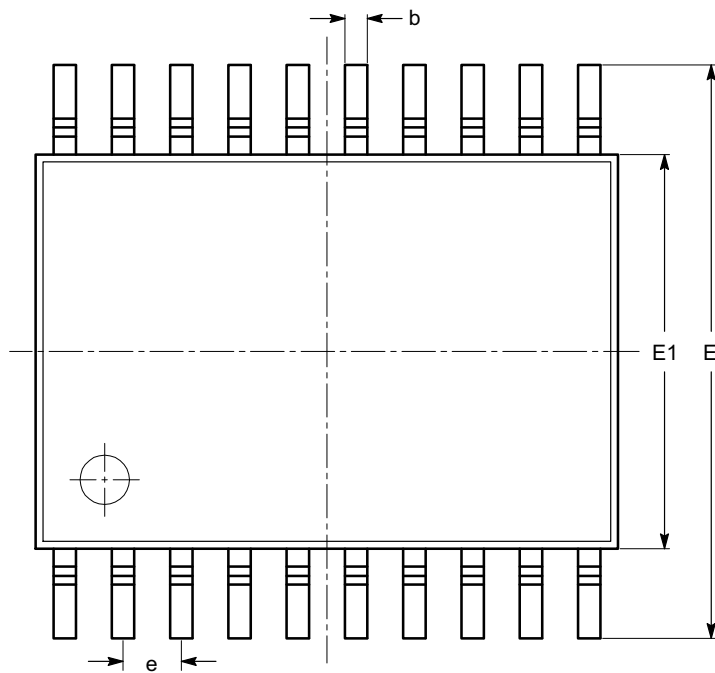
PACKAGE DIMENSIONS

ON Semiconductor®



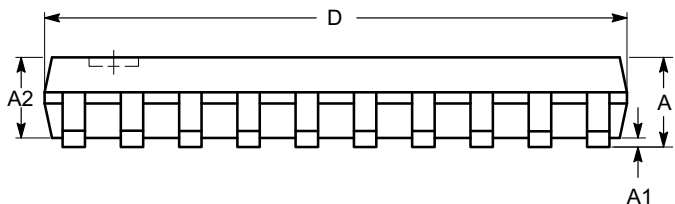
TSSOP20, 4.4x6.5
CASE 948AQ-01
ISSUE A

DATE 19 MAR 2009

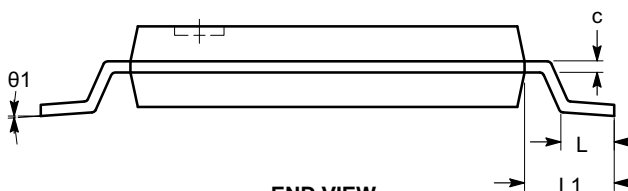


SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80		1.05
b	0.19		0.30
c	0.09		0.20
D	6.40	6.50	6.60
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
θ	0°		8°

TOP VIEW



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

DOCUMENT NUMBER:	98AON34453E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP20, 4.4X6.5	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales